To all our customers

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The semiconductor operations of Hitachi and Mitsubishi Electric were transferred to Renesas Technology Corporation on April 1st 2003. These operations include microcomputer, logic, analog and discrete devices, and memory chips other than DRAMs (flash memory, SRAMs etc.) Accordingly, although Mitsubishi Electric, Mitsubishi Electric Corporation, Mitsubishi Semiconductors, and other Mitsubishi brand names are mentioned in the document, these names have in fact all been changed to Renesas Technology Corp. Thank you for your understanding. Except for our corporate trademark, logo and corporate statement, no changes whatsoever have been made to the contents of the document, and these changes do not constitute any alteration to the contents of the document itself.

Note : Mitsubishi Electric will continue the business operations of high frequency & optical devices and power devices.

Renesas Technology Corp. Customer Support Dept. April 1, 2003



MITSUBISHI ICs (MONITOR)

M61314SP

I²C BUS CONTROLLED VIDEO PRE-AMP FOR HIGH RESOLUTION COLOR DISPLAY

DESCRIPTION

M61314SP is Semiconductor Integrated Circuit for CRT Display Monitor. It includes OSD Blanking,OSD Mixing,Retrace Blanking,Video detector,Sync Sepa ,Wide band Amplifer. Brightness Control, Main/Sub Contrast,OSD level, 4ch D/A OUT,Video response adjust can be controlled by I²C Bus.

FEATURES

Frequency Band Width

RGB: 180MHz (3Vp-p at -3dB) OSD: 80MHz

Input

RGB:0.7Vp-p(typical)OSD:3.5V~5V(positive)OSD BLK:3.5V~5V(positive)Retrace BLK:2.5V~5V(positive)Clamp Pulse:2.5V~5V(positive)

Output

RGB:	5Vp-p
	(at Brightness less than 2V DC)
OSD:	4Vp-p
	(at Brightness less than 2V DC)
Sync OUT:	5Vp-p

PIN CONFIGURATION (TOP VIEW) GND 32 NC(GND) RIN ABL IN 2 BO ROUT Vcc 1(12V) 3 29 Vcc 2(12V) GIN 4 SonG IN 28 GOUT GND1 27 GND4 6 26 BOUT BIN 25 NC(GND) GND2 8 24 D/A OUT 4 Sync Sepa.OUT 9 23 D/A OUT 3 Video det.OUT 10 22 D/A OUT 2 Vcc3(5V) 11 OSD BLK IN 21 D/A OUT 1 12 OSD R IN 20 SCL 13 OSD G IN 19 SDA 14 18 Clamp pulse IN OSD B IN 15 GND3 16 17 Ret.BLK IN Package:32P4B



32 pin plastic SDIP

RECOMMENDED OPERATING CONDITIONS

Supply Voltage Range	11.50V ~ 1	2.50V (V3,V29)
	4.75V ~ 5	5.25V (V11)
Rated Supply Voltage	12.00V	(V3,V29)
	5.00V	(V11)

APPLICATION EXAMPLE

CRT Display Monitor

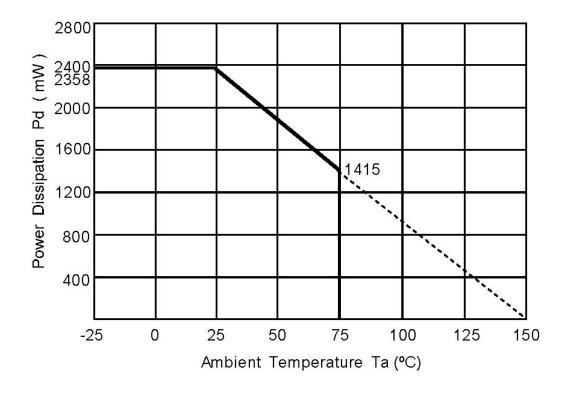


I²C BUS CONTROLLED VIDEO PRE-AMP FOR HIGH RESOLUTION COLOR DISPLAY

ABSOLUTE MAXIMUM RATINGS(Ambient temperature 25°C)

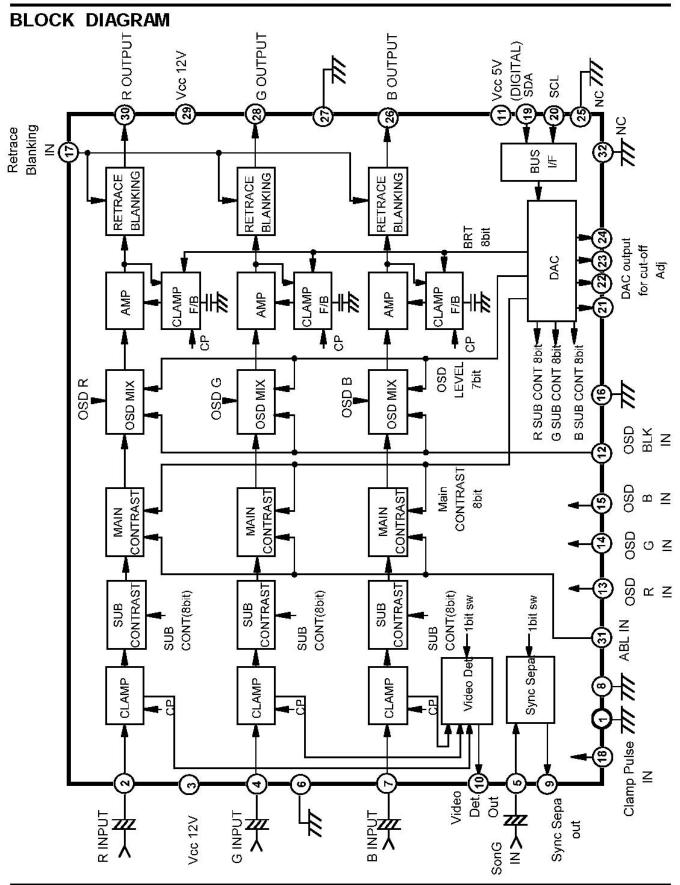
Parameter	Symbol	Rating	Unit
Supply voltage(Pin3,29)	Vcc12	13.0	V
Supply voltage(Pin11)	Vcc5	6.0	V
Power dissipation	Pd	2358	mW
Ambient temperature	Topr	-20 ~ +75	°C
Storage temperature	Tstg	-40 ~ +150	℃
Recommend supply 12	Vopr12	12.0	V
Recommend supply 5	Vopr5	5.0	V
Voltage range 12	Vopr'12	11.5 ~ 12.5	V
Voltage range 5	Vopr'5	4.75 ~ 5.25	V

THERMAL DERATING











MITSUBISHI ICs (MONITOR)

M61314SP

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BUS CONTROL TABLE

(1)Slave address:

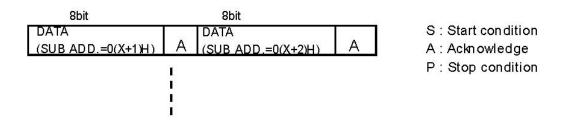
D7	D6	D5	D4	D3	D2	D1	R/W	
1	0	0	0	1	0	0	0	=88H

(2) Slave receiver format:

nor	mal	mode 8bit		8bit		8bit		
	S	SLAVE ADDRESS	А	SUB ADDRESS	А	DATA BYTE	A	Р

auto increment mode

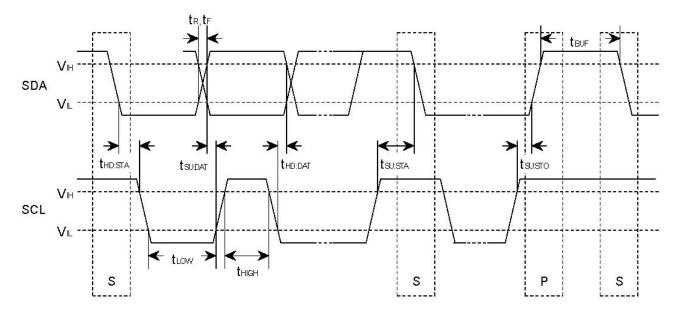
0	8bit	8bit			8bit		
s	SLAVE ADDRESS	А	SUB ADDRESS (0XH)+10H	A	DATA (SUB ADD.=0XH)	А	





SDA, SCL CHARACTERISTIC

parameter	symbol	MIN	MAX	unit
min. input LOW voltage	VL	-0.5	1.5	v
max. input HIGH voltage	VIH	3.0	5.5	v
SCL clock frequency.	fscL	0	400	KHz
Time the bus must be free before a new transmission can start.	teur	1.3	17 <u>20</u>	μs
Hold time start condition. After this period the first clock pulse is generated.	thd:sta	0.6	-	μs
The LOW period of the clock	tLOW	1.3	5 - 6	μs
The HIGH period of the clock	tнigн	0.6	-	μs
Set -up time for start condition.(Only relevant for a repeated Start condition.	t SU.STA	0.6		μs
Hold time DATA.	t HD:DAT	0	0.9	μs
Set-up time DATA	t su:dat	100		ns
Rise time both SDA and SCL lines.	tR	20+ 0.1Cb	300	ns
Fall time both SDA and SCL lines.	t⊧	20+ 0.1Cb	300	ns
Set-up time for stop condition	tsusto	0.6). - 3	μs





I²C BUS CONTROLLED VIDEO PRE-AMP FOR HIGH RESOLUTION COLOR DISPLAY

sub			Data Byte (top:byte format under:start condition)							
add.	function	bit	D7	D6	D5	D4	D3	D2	D1	DO
0011	Main contrast		A07	A06	A05	A04	A03	A02	A01	A00
00H	1	8	0	0	0	0	0	0	0	1
	Brightness		A17	A16	A15	A14	A13	A12	A11	A10
01H	control	8	0	0	0	0	0	0	0	1
02H	Sub contrast	8	A27	A26	A25	A24	A23	A22	A21	A20
028	R	•	0	0	0	0	0	0	0	1
03H	Sub contrast		A37	A36	A35	A34	A33	A32	A31	A30
038	G	8	0	0	0	0	0	0	0	1
0411	Sub contrast	8	A47	A46	A45	A44	A43	A42	A41	A40
04H	04H B	0	0	0	0	0	0	0	0	1
OFU	OCD lawal	7	_	A56	A55	A54	A53	A52	A51	A50
05H	OSD level	E C		0	0	0	0	0	0	1
0.011	D/A OUT1	8	A67	A66	A65	A64	A63	A62	A61	A60
06H			0	0	0	0	0	0	0	1
0700			A77	A76	A75	A74	A73	A72	A71	A70
07H	D/A OUT2	8	0	0	0	0	0	0	0	1
0011			A87	A86	A85	A84	A83	A82	A81	A80
08H	D/A OUT3	8	0	0	0	0	0	0	0	1
0011	DIA OUT	~	A97	A96	A95	A94	A93	A92	A91	A90
09H	D/A OUT4	8	0	0	0	0	0	0	0	1
0AH	Sharpness	4	-				AA3	AA2	AA1	AA0
UAN	control	4	·	-)=	-	0	0	0	1
	0 0 00		270	-	-	AA4	-		-	-
	Sync Sepa SW	1	22		-	0		2-0		-
			-	-	AA5		-	-	-	-
	Video Det SW	1	-	-	0	-	12	-		2
	T	2	AA7	AA6	i.			25	-	-
	Test mode	2	0	0	-	-	-	3.55		-

(3) Pre - Amp Block sub address byte and data byte format

*)pre-data

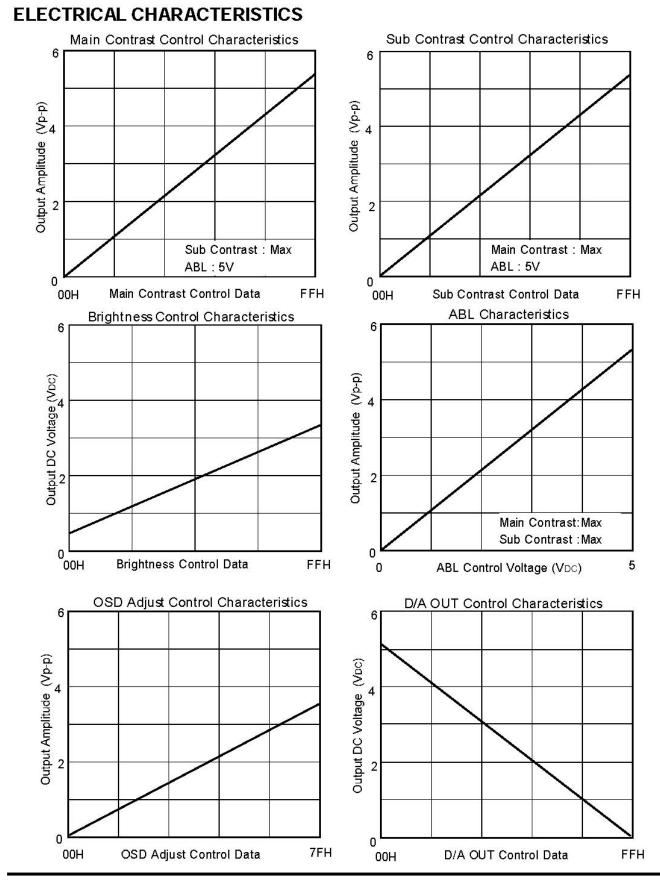
*)subadd. 0AH

Sync Sepa SW AA4 0:Sync Sepa ON 1:Sync Sepa OFF Video Det SW AA5 0:Video Det ON 1:Video Det OFF Always set up as AA6 and AA7 in 0

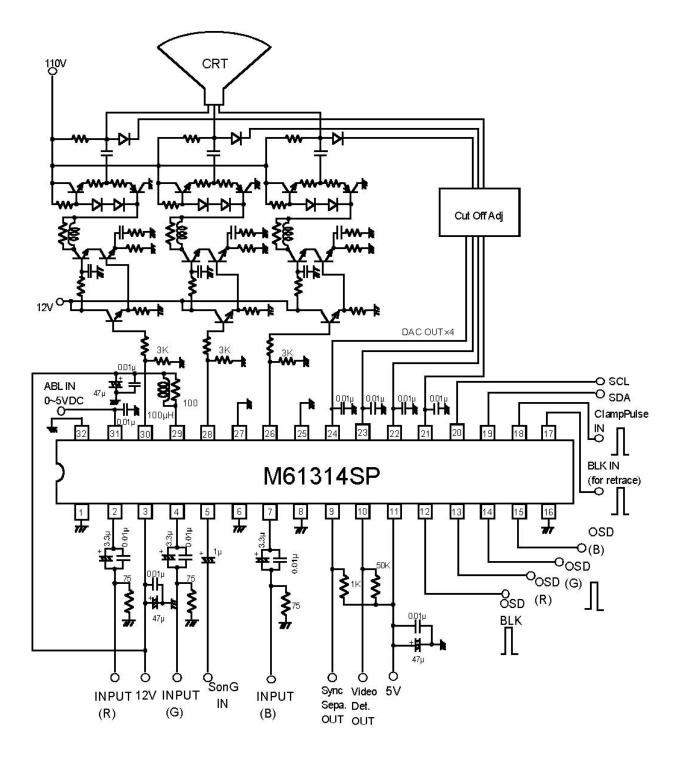
For IIC Data, please transfer in the period of Vertical.







APPLICATION EXAMPLE

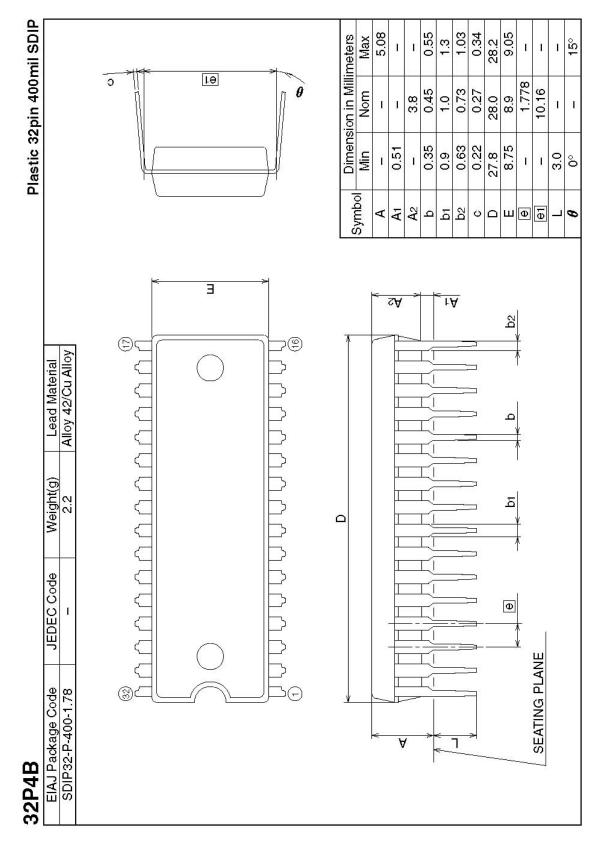


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I²C BUS CONTROLLED VIDEO PRE-AMP FOR HIGH RESOLUTION COLOR DISPLAY

DETAILED DIAGRAM OF PACKAGE OUTLINE





I²C BUS CONTROLLED VIDEO PRE-AMP FOR HIGH RESOLUTION COLOR DISPLAY

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